



REVISIONS				
REV.	ECN	DESCRIPTION	DATE	APPROVED
C		INITIAL RELEASE	APR 18/06	ML
D		PCB SOLDER PAD WIDTH REVISED FROM .010" TO .014"	FEB 19/07	ZLJ
E		TOLERANCE ADDED TO PCB HOLE & LOCATING PIN	FEB 27/07	ZLJ
F		FS1-R26-3000 ADDED	APR 05/07	JLJ
G		DIAM. PEG DIMS ADDED. TOLERANCE ADDED TO .472	AUG 06/07	ZLJ
H		HOUSING MODIFIED	AUG 23/07	ZLJ
J		IMPERIAL UNITS REMOVED	OCT 4/07	ZLJ

PART NUMBER	PACKAGING	CONTACT PLATING
FS1-R26-2000	TAPE AND REEL	30µ" GOLD OVER 50µ" NICKEL IN CONTACT AREAS 100µ" MATTE TIN OVER 50µ" NICKEL IN SOLDER AREAS
FS1-R26-3000		15µ" GOLD OVER 50µ" NICKEL IN CONTACT AREAS 100µ" MATTE TIN OVER 50µ" NICKEL IN SOLDER AREAS

- NOTES:
- MATERIAL:
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
 - ROHS COMPLIANT
 - PERFORMANCE:
ELECTRICAL: 0.5 AMPS MAX. PER CONTACT
MECHANICAL: 250 MATING CYCLES MINIMUM
 - COMPLIES WITH SFF-8086



RECOMMENDED PCB LAYOUT

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

DO NOT SCALE DRAWING

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:	APPROVALS	DATE	Amphenol Canada Corp.
DECIMALS .XX ± 0.25	DRAWN YK	15/FEB/06	
ANGLES ± 2°	CHECKED YK	15/FEB/06	FILE
MATERIAL AND FINISH	DATE APP'D		SFF, 26 POSITION CONNECTOR
ENGR. REV. EAR	DATE APP'D		REV. J
CODE IDENT. NO. 03554	DATE APP'D		REV. C
			NTS
			SFF
			SHEET 1 OF 1